



## Materials Declaration Form

<b>IPC</b>	1752	<b>Version</b>	2
<b>Form Type *</b>	Distribute		
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D  <i>* : Required Field</i>

<b>Supplier Information</b>			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2021-05-19
<b>Company Unique ID</b>	NL 008751171B01		
<b>Contact Name *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	giovanni giacopello	<b>Representative Title</b>	ADG Material Declaration champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**


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<b>Legal Statement</b>			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STTH30AC06CWL	HFWT*P21B22O	A	998G	2021-05-19
	Amount	UoM	Unit type	ST ECOPACK Grade
	6100	mg	Each	ECOPACK 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
Not Applicable	Not Applicable	.		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	DM00756247	

Package Designator	Package Size	Nbr of instances	Shape	
SIP	15.80,21.00,5.00	3	Through hole	
Comment	TO-247 LONG LEADS			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : ELV directive : 2000/53/EC amended 2020/363_March 2020	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	true
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Exemption Id.	Description

QueryList : California Prop65 list, dated 18th December 2020			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			false
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			true
Substance	amount in product (mg)	Application	ppm in product
Nickel	20.26	die - leadframe	3322

QueryList : REACH-19th January 2021				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material

QueryList : Responsible metals sourcing	
Query	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present is the component :	Gold, Tin,
This product is in the scope of the responsible metals sourcing, its compliance is covered by our company processes .	

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	HFWT*P21B220					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	10.381	mg	supplier	die	Silicon(Si)	7440-21-3		9.982	mg	961565	1636
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.062	mg	5972	10
				supplier	metallisation	Gold(Au)	7440-57-5		0.015	mg	1445	2
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.068	mg	6550	11
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.005	mg	482	1
				supplier	passivation	Silicon oxide	7631-86-9		0.061	mg	5878	10
Leadframe	M-004 Copper and its alloys	4038.980	mg	supplier	polymer coating	Durimide	proprietary		0.188	mg	18110	31
				supplier	alloy	Copper(Cu)	7440-50-8		4013.534	mg	993700	657956
				supplier	alloy	Nickel(Ni)	7440-02-0		20.195	mg	5000	3311
				supplier	alloy	Iron(Fe)	7439-89-6		4.039	mg	1000	862
				supplier	alloy	Phosphorus metal	7723-14-0		1.212	mg	300	199
				supplier	solder	Tin(Sn)	7440-31-5		2.574	mg	650000	422
Soft solder	Solder	3.960	mg	supplier	solder	Silver(Ag)	7440-22-4		0.990	mg	250000	162
				supplier	solder	Antimony (Sb)	7440-36-0		0.396	mg	100000	65
				supplier	wire	Aluminium (Al)	7429-90-5		6.457	mg	1000000	1059
				supplier	alloy	Phosphorus metal	7723-14-0		1.212	mg	300	199
Bonding wires	M-003 Aluminum and its alloys	6.457	mg	supplier	wire	Aluminium (Al)	7429-90-5		6.457	mg	1000000	1059
				supplier	mold compound	Silica vitreous	60676-86-0		1521.203	mg	760000	249378
				supplier	mold compound	Epoxy Cresol Novolac	29690-82-2		310.245	mg	155000	50860
				supplier	mold compound	Phenolic resin	9003-35-4		60.048	mg	30000	9844
				supplier	mold compound	Metal hydroxide	proprietary		100.079	mg	50000	16406
Encapsulation	M-011 Other inorganic materials	2001.583	mg	supplier	mold compound	Carbon black	1333-86-4		10.008	mg	5000	1641
				supplier	mold compound	Carbon black	1333-86-4		10.008	mg	5000	1641
				supplier	solder alloy	Tin (Sn)	7440-31-5		38.639	mg	1000000	6334
Connections coating	Solder	38.639	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		38.639	mg	1000000	6334